

U.2 SSD

3TG3-P Series

Customer: _____

Customer

Part

Number: _____

Innodisk

Part

Number: _____

Innodisk

Model Name: _____

Date: _____

| Innodisk Approver | Customer Approver |
|--------------------------|--------------------------|
| | |

**Total Solution For
Industrial Flash Storage**

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REVISION HISTORY

| Revision | Description | Date |
|-----------------|--------------------------------|------------|
| Preliminary 1.0 | First release | Dec, 2020 |
| V1.1 | Revise Product View and Models | Jan., 2023 |

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1. Product Overview

1.1 Introduction of Innodisk U.2 SSD 3TG3-P

Innodisk U.2 SSD 3TG3-P is an NVM Express SSD designed as PCIe SFF-8639 module with PCIe interface and 3D TLC NAND Flash. U.2 SSD3TG3-P supports PCIe Gen III x4, and it is compliant with NVMe 1.3 providing excellent performance. With sophisticated error detection and correction (ECC) functions, the module can ensure full End-to-end Data Path Protection that secures the data transmission between host system and NAND Flash.

Innodisk U.2 SSD 3TG3-P provides ultra-speed and high IOPS and offers maximum capacity up to 2TB, making the SSD optimal for server and heavy data workload applications.

CAUTION *TRIM must be enabled.*

TRIM enables SSD's controller to skip invalid data instead of moving. It can free up significant amount of resources, extends the lifespan of SSD by reducing erase, and write cycles on the SSD. Innodisk's handling of garbage collection along with TRIM command improves write performance on SSDs.

1.2 Product View and Models

Innodisk U.2 SSD 3TG3-P is available in follow capacities within 3D TLC flash ICs.

U.2 SSD 3TG3-P 128GB

U.2 SSD 3TG3-P 256GB

U.2 SSD 3TG3-P 512GB

U.2 SSD 3TG3-P 1TB

U.2 SSD 3TG3-P 2TB



Figure 1: Innodisk U.2 SSD 3TG3-P

PCIe Interface

Innodisk U.2 SSD 3TG3-P supports PCIe Gen III interface and compliant with NVMe 1.3. U.2 SSD 3TG3-P can work under PCIe Gen 1, Gen 2 and Gen 3.

Most of operating system includes NVMe in-box driver now. For more information about the driver support in each OS, please visit <http://nvmexpress.org/resources/drivers>.

2. Product Specifications

2.1 Capacity and Device Parameters

U.2 SSD 3TG3-P device parameters are shown in Table 1.

Table 1: Device parameters

| Capacity | LBA | User Capacity(GB) |
|----------|------------|-------------------|
| 128GB | 250069680 | 119.24GB |
| 256GB | 500118192 | 238.47GB |
| 512GB | 1000215216 | 476.94GB |
| 1TB | 2000409264 | 953.87GB |
| 2TB | 4000797360 | 1907.73GB |

2.2 Performance

Burst Transfer Rate: 32.0Gbps

Table 2: Performance

| Capacity | 128GB | 256GB | 512GB | 1TB | 2TB |
|-----------------------------|----------|-----------|-----------|-----------|-----------|
| Sequential* Read (max.) | 950 MB/s | 1900 MB/s | 3500MB/s | 3500 MB/s | 3500 MB/s |
| Sequential* Write (max.) | 500 MB/s | 1000 MB/s | 2100 MB/s | 2800 MB/s | 2900 MB/s |
| 4KB Random* Read (QD32) | 53,000 | 106,000 | 200,000 | 307,000 | 338,000 |
| 4KB Random* Write (QD32) | 129,000 | 261,000 | 299,000 | 300,000 | 308,000 |

Note: Performance results are measured in Room Temperature with Out-of-Box devices and may vary depending on overall system setup. Performance results are based on CrystalDiskMark 6.0.2 with file size 1000MB.

*Unit of 4KB items is I.O.P.S.

2.3 Electrical Specifications

2.3.1 Power Requirement

Table 3: Innodisk U.2 SSD 3TG3-P Power Requirement

| Item | Symbol | Rating | Unit |
|---------------|-----------------|--------------|------|
| Input voltage | V _{IN} | +12 DC +- 5% | V |

2.3.2 Power Consumption

Table 4: Power Consumption

| Mode | Power Consumption (mA) |
|-------------|------------------------|
| Read(rms.) | 456 |
| Write(rms.) | 666 |
| Idle(rms.) | 174 |
| Peak | 1490 |

* Target: 2TB U.2 SSD 3TG3-P

2.4 Environmental Specifications

2.4.1 Temperature Ranges

Table 5: Temperature range for U.2 SSD 3TG3-P

| Temperature | Range |
|-------------|---|
| Operating | Standard Grade: 0°C to +70°C Industrial Grade: -40°C ~ +85°C |
| Storage | -40°C ~ +85°C |

2.4.2 Humidity

Relative Humidity: 10-95%, non-condensing

2.4.3 Shock and Vibration

Table 6: Shock/Vibration Testing for U.2 SSD 3TG3-P

| Reliability | Test Conditions | Reference Standards |
|------------------|---------------------------------|---------------------|
| Vibration | 7 Hz to 2K Hz, 20G, 3 axes | IEC 60068-2-6 |
| Mechanical Shock | Duration: 0.5ms, 1500 G, 3 axes | IEC 60068-2-27 |

2.4.4 Mean Time between Failures (MTBF)

Table 7 summarizes the MTBF prediction results for various U.2 SSD 3TG3-P configurations. The analysis was performed using a RAM Commander™ failure rate prediction.

- **Failure Rate:** The total number of failures within an item population, divided by the total number of life units expended by that population, during a particular measurement interval under stated condition.
- **Mean Time between Failures (MTBF):** A basic measure of reliability for repairable items: The mean number of life units during which all parts of the item perform within their specified limits, during a particular measurement interval under stated conditions.

Table 7: U.2 SSD 3TG3-P MTBF

| Product | Condition | MTBF (Hours) |
|-------------------------|---------------------------|--------------|
| Innodisk U.2 SSD 3TG3-P | Telcordia SR-332 GB, 25°C | >3,000,000 |

2.5 CE and FCC Compatibility

U.2 SSD 3TG3-P conforms to CE and FCC requirements.

2.6 RoHS Compliance

U.2 SSD 3TG3-P is fully compliant with RoHS directive.

2.7 Reliability

Table 8: U.2 SSD 3TG3-P TBW

| Parameter | Value(ST) | Value(WT) | | |
|---|---|---|---------------------|-----------------|
| Read Cycles | Unlimited Read Cycles | | | |
| Flash endurance | 10,000 P/E cycles | 3,000 P/E cycles | | |
| Wear-Leveling Algorithm | Support | | | |
| Bad Blocks Management | Support | | | |
| Error Correct Code | Support(LDPC) | | | |
| Data Retention | 5 Years at Initial NAND Status 4 Months at NAND Life End | 10 Years at Initial NAND Status 2 Years at NAND Life End | | |
| TBW* (Total Bytes Written) Unit: TB | | | | |
| Capacity | ST | | WT | |
| | Sequential workload | Client workload | Sequential workload | Client workload |
| 128GB | TBD | TBD | TBD | TBD |
| 256GB | TBD | TBD | TBD | TBD |
| 512GB | TBD | TBD | TBD | TBD |
| 1TB | TBD | TBD | TBD | TBD |
| 2TB | TBD | TBD | TBD | TBD |
| * Note: | | | | |
| 1. Sequential: Mainly sequential write, tested by Vdbench. These are estimated values subject to update. | | | | |
| 2. Client: Follow JESD218 Test method and JESD219A Workload, tested by ULINK. (The capacity lower than 64GB client workload is not specified in JEDEC219A, the values are estimated.) | | | | |
| 3. Based on out-of-box performance. | | | | |

2.8 Transfer Mode

U.2 SSD 3TG3-P support following transfer mode:

PCIe Gen III 4 GB/s

PCIe Gen II 2 GB/s

PCIe Gen I 1 GB/s

2.9 Pin Assignment

Innodisk U.2 SSD 3TG3-P follows standard SFF-8639 spec as below. Mechanical details are documented in SFF-8639: Multifunction 6X Unshielded Connector.

Table 9: Innodisk U.2 SSD 3TG3-P Pin Assignment

| Pin | Mate | Name |
|-----|------|----------------|
| P1 | 3rd | WAKE# |
| P2 | 3rd | - |
| P3 | 2nd | PWRDIS |
| P4 | 1st | IfDet# |
| P5 | 2nd | Ground |
| P6 | 2nd | Ground |
| P7 | 2nd | - |
| P8 | 3rd | - |
| P9 | 3rd | - |
| P10 | 2nd | - |
| P11 | 3rd | ACTIVITY# |
| P12 | 1st | Ground |
| P13 | 2nd | +12V Precharge |
| P14 | 3rd | +12V |
| P15 | 3rd | +12V |
| S1 | 2nd | Ground |
| S2 | 3rd | - |
| S3 | 3rd | - |
| S4 | 2nd | Ground |
| S5 | 3rd | - |
| S6 | 3rd | - |
| S7 | 2nd | Ground |
| S8 | 2nd | Ground |
| S9 | 3rd | - |
| S10 | 3rd | - |
| S11 | 2nd | Ground |
| S12 | 3rd | - |
| S13 | 3rd | - |
| S14 | 2nd | Ground |
| S15 | 3rd | - |
| S16 | 2nd | Ground |

| | | |
|------------|-------------|-------------|
| S17 | 3rd | PETp1 |
| Pin | Mate | Name |
| S18 | 3rd | PETn1 |
| S19 | 2nd | Ground |
| S20 | 3rd | PERn1 |
| S21 | 3rd | PERp1 |
| S22 | 2nd | Ground |
| S23 | 3rd | PETp2 |
| S24 | 3rd | PETn2 |
| S25 | 2nd | Ground |
| S26 | 3rd | PERn2 |
| S27 | 3rd | PERp2 |
| S28 | 2nd | Ground |
| E1 | 3rd | - |
| E2 | 3rd | - |
| E3 | 3rd | - |
| E4 | 3rd | - |
| E5 | 3rd | PERST# |
| E6 | 3rd | - |
| E7 | 3rd | - |
| E8 | 3rd | - |
| E9 | 2nd | Ground |
| E10 | 3rd | PETp0 |
| E11 | 3rd | PETn0 |
| E12 | 2nd | Ground |
| E13 | 3rd | PERn0 |
| E14 | 3rd | PERp0 |
| E15 | 2nd | Ground |
| E16 | 3rd | - |
| E17 | 3rd | PETp3 |
| E18 | 3rd | PETn3 |
| E19 | 2nd | Ground |
| E20 | 3rd | PERn3 |
| E21 | 3rd | PERp3 |
| E22 | 2nd | Ground |
| E23 | 3rd | - |
| E24 | 3rd | - |
| E25 | 3rd | - |

2.10 Mechanical Dimensions

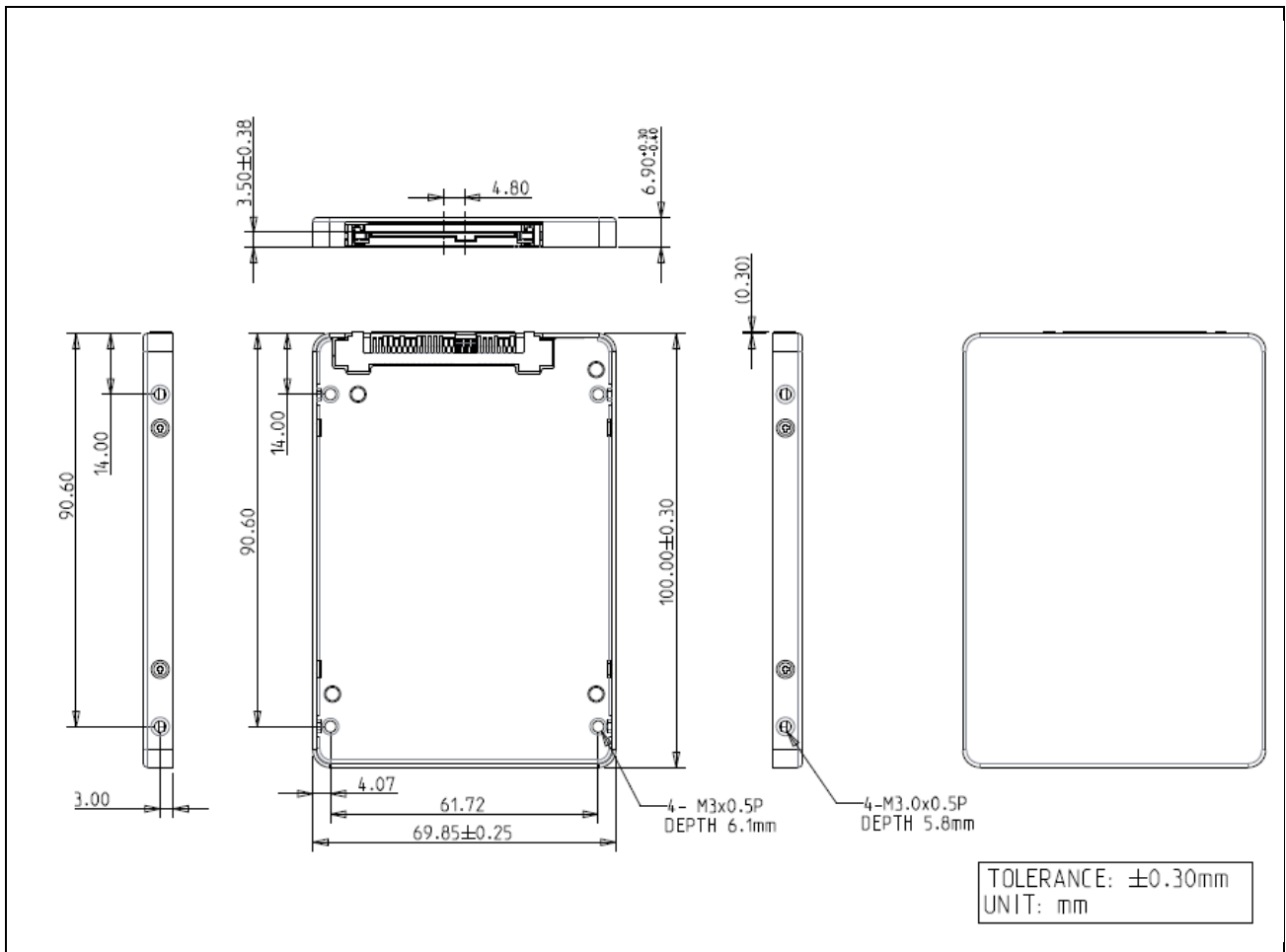


Figure 2: Innodisk U.2 SSD 3TG3-

2.11 Assembly Weight

An Innodisk U.2 SSD 3TG3-P within NAND flash ICs, 128GB's weight is 7 grams approximately.

2.12 Seek Time

Innodisk U.2 SSD 3TG3-P is not a magnetic rotating design. There is no seek or rotational latency required.

2.13 NAND Flash Memory

Innodisk U.2 SSD 3TG3-P uses 3D TLC NAND flash memory, which is non-volatility, high reliability and high speed memory storage.

3. Theory of Operation

3.1 Overview

Figure 2 shows the operation of Innodisk U.2 SSD 3TG3-P from the system level, including the major hardware blocks.

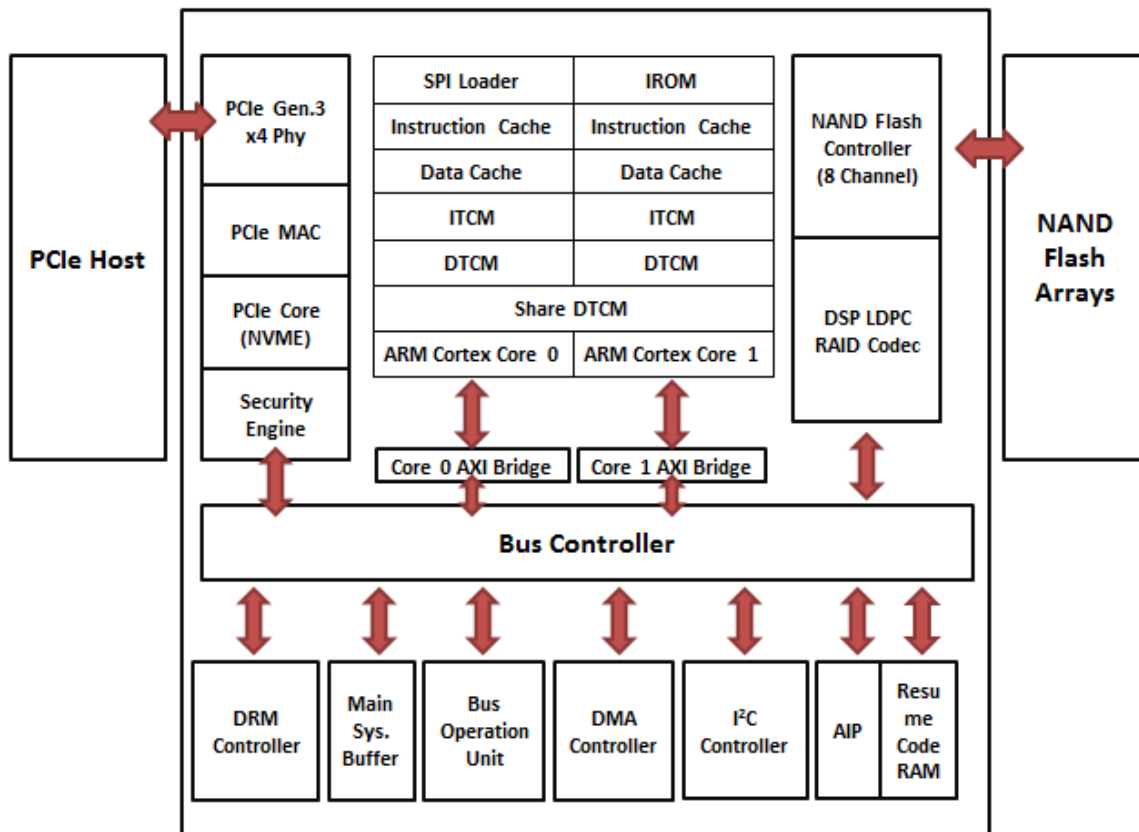


Figure 3: Innodisk U.2 SSD 3TG3-P Block Diagram

Innodisk U.2 SSD 3TG3-P integrates a PCIe Gen III x4 controller and NAND flash memories. Communication with the host occurs through the host interface, using the standard NVM protocol. Communication with the flash device(s) occurs through the flash interface.

3.2 PCIe Gen III x4 Controller

Innodisk U.2 SSD 3TG3-P is a PCIe Gen IIx4 controller is compliant with NVMe 1.3, up to 32.0Gbps transfer speed. Also it is compliant with PCIe Gen 1, Gen 2 and Gen 3 specification. The controller supports up to 8 channels for flash interface.

3.3 Error Detection and Correction

Innodisk U.2 SSD 3TG3-P is designed with hardware LDPC ECC engine with hard-decision and soft-decision decoding. Low-density parity-check (LDPC) codes have excellent error correcting performance close to the Shannon limit when decoded with the belief-propagation (BP) algorithm using soft-decision information.

3.4 Wear-Leveling

Flash memory can be erased within a limited number of times. This number is called the **erase cycle limit** or **write endurance limit** and is defined by the flash array vendor. The erase cycle limit applies to each individual erase block in the flash device.

Innodisk U.2 SSD 3TG3-P uses a combination of two types of wear leveling- dynamic and static wear leveling- to distribute write cycling across an SSD and balance erase count of each block, thereby extending flash lifetime.

3.5 Bad Blocks Management

Bad Blocks are blocks that contain one or more invalid bits whose reliability are not guaranteed. The Bad Blocks may be presented while the SSD is shipped, or may develop during the life time of the SSD. When the Bad Blocks is detected, it will be flagged, and not be used anymore. The SSD implement Bad Blocks management, Bad Blocks replacement, Error Correct Code to avoid data error occurred. The functions will be enabled automatically to transfer data from Bad Blocks to spare blocks, and correct error bit.

3.6 iData Guard

Innodisk's iData Guard is a comprehensive data protection mechanism that functions before and after a sudden power outage to the SSD. Low-power detection terminates data writing before an abnormal power-off, while table-remapping after power-on deletes corrupt data and maintains data integrity. Innodisk's iData Guard provides effective power cycling management, preventing data stored in flash from degrading with use.

3.7 Garbage Collection/TRIM

Garbage collection and TRIM technology is used to maintain data consistency and perform continual data cleansing on SSDs. It runs as a background process, freeing up valuable controller resources while sorting good data into available blocks, and deleting bad blocks. It also significantly reduces write operations to the drive, thereby increasing the SSD's speed and lifespan.

3.8 End to End Data Path Protection

End-to-end Data Path Protection that secures the data transmission between host system and NAND Flash. In the transmission path, no matter in or out, all buffer and storage implement Error Code Correction that optimizes the data integrity in the whole transmission of SSD.

3.9 Thermal Management

U.2 SSD 3TG3-P has built-in thermal sensor which can detect environment temperature of SSD. In the meantime, firmware will monitor the thermal sensor to prevent any failure of overheating. During extreme temperature, firmware will adjust the data transfer behavior to maintain the SSD's reliable operation.

4. Installation Requirements

4.1 U.2 SSD 3TG3-P Pin Directions

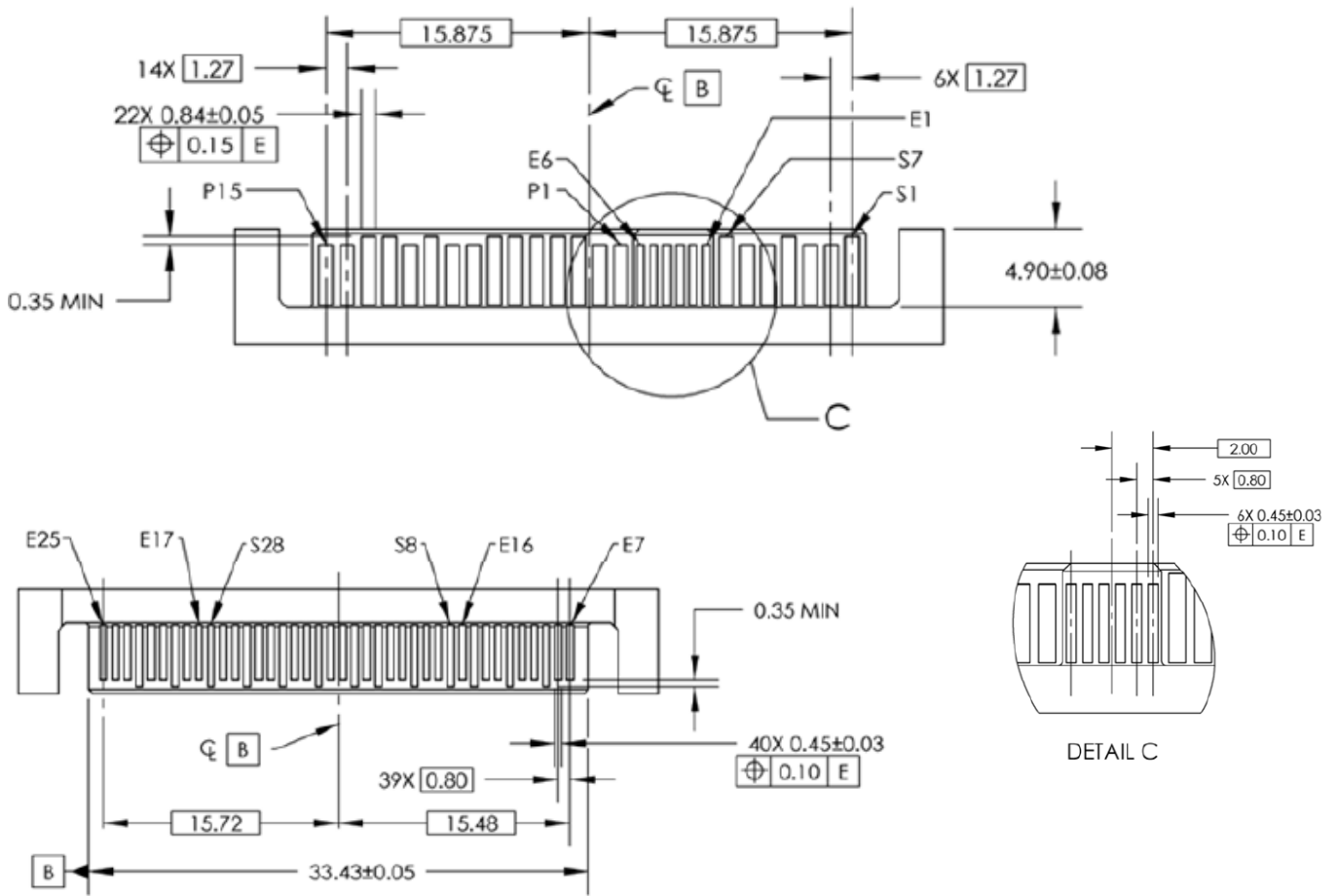


Figure 4: Device Signal Segment Power Segment

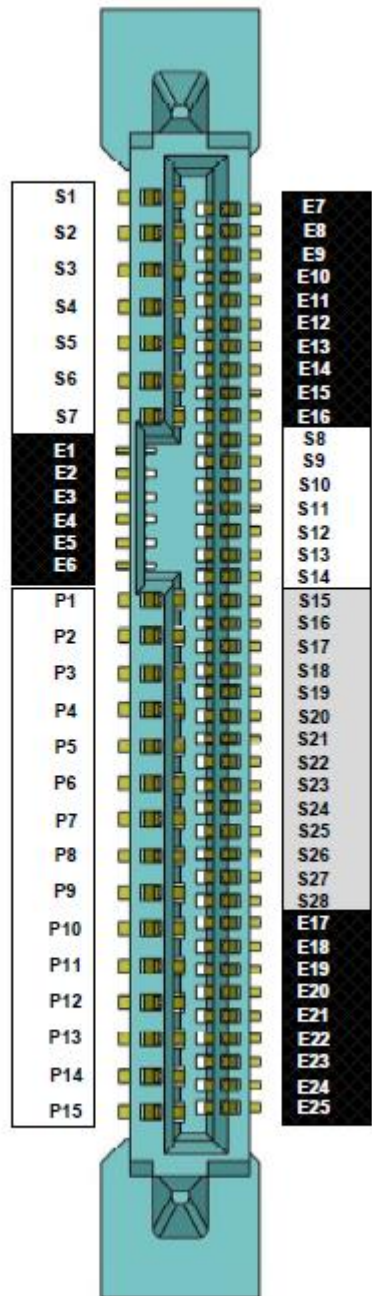


Figure 5: Signal Segment and Power Segment(Host/cable side)

4.2 Electrical Connections for U.2 SSD 3TG3-P

U.2 SSD 3TG3-P follows standard SFF-8639 spec, Mechanical details are documented in SFF-8639: Multifunction 6X Unshielded Connector, it is a total of 68 contacts, not all contacts may be utilized. U.2 SSD 3TG3-P only support PCIe interface, see more details in *2.9 Pin Assignment*.

4.3 Device Drive

U.2 (P80) 3TG3-P is compliant with NVMe 1.3. Both Operation System and BIOS should include NVMe driver to compatible with NVMe device. Nowadays, most of OS includes NVMe in-box

driver now. For more information about the driver support in each OS, please visit the website <http://nvmeexpress.org/resources/drivers>. For BIOS NVMe driver support please contact with motherboard manufacturers.

5. SMART / Health Information

This log page is used to provide SMART and general health information. The information provided is over the life of the controller and is retained across power cycles. More details about Set Features command; please refer to NVM Express 1.3

5.1 Get Log Page(Log Identifier 02h)

Innodisk 3TG3-P series SMART / Health Information Log are listed in following table.

Table 10: Get Log Page – SMART / Health Information Log

| Bytes | Description | | | | | | | | | | | | | | |
|-------|--|-----|------------|----|---|----|--|----|--|----|--|----|--|-------|----------|
| 0 | <p>Critical Warning: This field indicates critical warnings for the state of the controller. Each bit corresponds to a critical warning type; multiple bits may be set. If a bit is cleared to '0', then that critical warning does not apply. Critical warnings may result in an asynchronous event notification to the host. Bits in this field represent the current associated state and are not persistent.</p> <table border="1"> <thead> <tr> <th>Bit</th> <th>Definition</th> </tr> </thead> <tbody> <tr> <td>00</td> <td>If set to '1', then the available spare space has fallen below the threshold.</td> </tr> <tr> <td>01</td> <td>If set to '1', then a temperature is above an over temperature threshold or below an under</td> </tr> <tr> <td>02</td> <td>If set to '1', then the NVM subsystem reliability has been degraded due to significant media related</td> </tr> <tr> <td>03</td> <td>If set to '1', then the media has been placed in read only mode.</td> </tr> <tr> <td>04</td> <td>If set to '1', then the volatile memory backup device has failed. This field is only valid if the</td> </tr> <tr> <td>07:05</td> <td>Reserved</td> </tr> </tbody> </table> | Bit | Definition | 00 | If set to '1', then the available spare space has fallen below the threshold. | 01 | If set to '1', then a temperature is above an over temperature threshold or below an under | 02 | If set to '1', then the NVM subsystem reliability has been degraded due to significant media related | 03 | If set to '1', then the media has been placed in read only mode. | 04 | If set to '1', then the volatile memory backup device has failed. This field is only valid if the | 07:05 | Reserved |
| Bit | Definition | | | | | | | | | | | | | | |
| 00 | If set to '1', then the available spare space has fallen below the threshold. | | | | | | | | | | | | | | |
| 01 | If set to '1', then a temperature is above an over temperature threshold or below an under | | | | | | | | | | | | | | |
| 02 | If set to '1', then the NVM subsystem reliability has been degraded due to significant media related | | | | | | | | | | | | | | |
| 03 | If set to '1', then the media has been placed in read only mode. | | | | | | | | | | | | | | |
| 04 | If set to '1', then the volatile memory backup device has failed. This field is only valid if the | | | | | | | | | | | | | | |
| 07:05 | Reserved | | | | | | | | | | | | | | |
| 2:1 | <p>Composite Temperature: Contains a value corresponding to a temperature in degrees Kelvin that represents the current composite temperature of the controller and namespace(s) associated with that controller. The manner in which this value is computed is implementation specific and may not represent the actual temperature of any physical point in the NVM subsystem. The value of this field may be used to trigger an asynchronous event.</p> | | | | | | | | | | | | | | |

| | |
|-------|---|
| | Warning and critical overheating composite temperature threshold values are reported by the WCTEMP and CCTEMP fields in the Identify Controller data structure. |
| 3 | Available Spare: Contains a normalized percentage (0 to 100%) of the remaining spare capacity available. |
| 4 | Available Spare Threshold: When the Available Spare falls below the threshold indicated in this field, an asynchronous event completion may occur. The value is indicated as a normalized percentage (0 to 100%). |
| 5 | Percentage Used: Contains a vendor specific estimate of the percentage of NVM subsystem life used based on the actual usage and the manufacturer's prediction of NVM life. A value of 100 indicates that the estimated endurance of the NVM in the NVM subsystem has been consumed, but may not indicate an NVM subsystem failure. The value is allowed to exceed 100. Percentages greater than 254 shall be represented as 255. This value shall be updated once per power-on hour (when the controller is not in a sleep state). Refer to the JEDEC JESD218A standard for SSD device life and endurance measurement techniques. |
| 31:6 | Reserved |
| 47:32 | Data Units Read: Contains the number of 512 byte data units the host has read from the controller; this value does not include metadata. This value is reported in thousands (i.e., a value of 1 corresponds to 1000 units of 512 bytes read) and is rounded up. When the LBA size is a value other than 512 bytes, the controller shall convert the amount of data read to 512 byte units. For the NVM command set, logical blocks read as part of Compare and Read operations shall be included in this value. |
| 63:48 | Data Units Written: Contains the number of 512 byte data units the host has written to the controller; this value does not include metadata. This value is reported in thousands (i.e., a value of 1 corresponds to 1000 units of 512 bytes written) and is rounded up. When the LBA size is a value other than 512 bytes, the controller shall convert the amount of data written to 512 byte units. For the NVM command set, logical blocks written as part of Write operations shall be included in this value. Write Uncorrectable commands shall not impact this value. |
| 79:64 | Host Read Commands: Contains the number of read commands completed by the controller. For the NVM command set, this is the number of Compare and Read commands. |

| | |
|---------|---|
| 95:80 | <p>Host Write Commands: Contains the number of write commands completed by the controller.</p> <p>For the NVM command set, this is the number of Write commands.</p> |
| 111:96 | <p>Controller Busy Time: Contains the amount of time the controller is busy with I/O commands. The controller is busy when there is a command outstanding to an I/O Queue (specifically, a command was issued via an I/O Submission Queue Tail doorbell write and the corresponding completion queue entry has not been posted yet to the associated I/O Completion Queue). This value is reported in minutes.</p> |
| 127:112 | <p>Power Cycles: Contains the number of power cycles.</p> |
| 143:128 | <p>Power On Hours: Contains the number of power-on hours. This may not include time that the controller was powered and in a non-operational power state.</p> |
| 159:144 | <p>Unsafe Shutdowns: Contains the number of unsafe shutdowns. This count is incremented when a shutdown notification (CC.SHN) is not received prior to loss of power.</p> |
| 175:160 | <p>Media and Data Integrity Errors: Contains the number of occurrences where the controller detected an unrecovered data integrity error. Errors such as uncorrectable ECC, CRC checksum failure, or LBA tag mismatch are included in this field.</p> |
| 191:176 | <p>Number of Error Information Log Entries: Contains the number of Error Information log entries over the life of the controller.</p> |
| 195:192 | <p>Warning Composite Temperature Time: Contains the amount of time in minutes that the controller is operational and the Composite Temperature is greater than or equal to the Warning Composite Temperature Threshold (WCTEMP) field and less than the Critical Composite Temperature Threshold (CCTEMP) field in the Identify Controller data structure.</p> <p>If the value of the WCTEMP or CCTEMP field is 0h, then this field is always cleared to 0h regardless of the Composite Temperature value.</p> |
| 199:196 | <p>Critical Composite Temperature Time: Contains the amount of time in minutes that the controller is operational and the Composite Temperature is greater than the Critical Composite Temperature Threshold (CCTEMP) field in the Identify Controller data structure.</p> <p>If the value of the CCTEMP field is 0h, then this field is always cleared to 0h regardless of the Composite Temperature value.</p> |
| 201:200 | <p>Temperature Sensor 1: Contains the current temperature reported by temperature sensor 1.</p> |
| 203:202 | <p>Temperature Sensor 2: Contains the current temperature reported by temperature sensor 2.</p> |

| | |
|---------|--|
| 205:204 | Temperature Sensor 3: Contains the current temperature reported by temperature sensor 3. |
| 207:206 | Temperature Sensor 4: Contains the current temperature reported by temperature sensor 4. |
| 209:208 | Temperature Sensor 5: Contains the current temperature reported by temperature sensor 5. |
| 211:210 | Temperature Sensor 6: Contains the current temperature reported by temperature sensor 6. |
| 213:212 | Temperature Sensor 7: Contains the current temperature reported by temperature sensor 7. |
| 215:214 | Temperature Sensor 8: Contains the current temperature reported by temperature sensor 8. |
| 219:216 | Thermal Management Temperature 1 Transition Count: Contains the number of times the controller transitioned to lower power active power states or performed vendor specific thermal management actions while minimizing the impact on performance in order to attempt to reduce the Composite Temperature because of the host controlled thermal management feature (refer to section 8.4.5) (i.e., the Composite Temperature rose above the Thermal Management Temperature 1.) This counter shall not wrap once it reaches its maximum value. A value of zero, indicates that this transition has never occurred or this field is not implemented. |
| 223:220 | Thermal Management Temperature 2 Transition Count: Contains the number of times the controller transitioned to lower power active power states or performed vendor specific thermal management actions regardless of the impact on performance (e.g., heavy throttling) in order to attempt to reduce the Composite Temperature because of the host controlled thermal management feature (refer to section 8.4.5) (i.e., the Composite Temperature rose above the Thermal Management Temperature 2.) This counter shall not wrap once it reaches its maximum value. A value of zero, indicates that this transition has never occurred or this field is not implemented. |
| 227:224 | Total Time For Thermal Management Temperature 1: Contains the number of seconds that the controller had transitioned to lower power active power states or performed vendor specific thermal management actions while minimizing the impact on performance in order to attempt to reduce the Composite Temperature because of the host controlled thermal management feature (refer to section 8.4.5). This counter shall not wrap once it reaches its maximum value. A value of zero, indicates that this transition has never occurred or this field is not implemented. |

| | |
|---------|--|
| 231:228 | <p>Total Time For Thermal Management Temperature 2: Contains the number of seconds that the controller had transitioned to lower power active power states or performed vendor specific thermal management actions regardless of the impact on performance (e.g., heavy throttling) in order to attempt to reduce the Composite Temperature because of the host controlled thermal management feature (refer to section 8.4.5). This counter shall not wrap once it reaches its maximum value. A value of zero, indicates that this transition has never occurred or this field is not implemented.</p> |
| 511:232 | <p>Reserved</p> |

Notes: More detailed health info has been defined by innodisk and will be shown on iSMART V5.3.21 (or later version).

7. Part Number Rule

| CODE | 1 | 2 | 3 | 4 | 5 | 6 | 7 | 8 | 9 | 10 | 11 | 12 | 13 | 14 | 15 | 16 | 17 | 18 | 19 | 20 | 21 |
|--|---|---|-----------|---|---|-----------|---|---|---|----|--|----|----|----|----|----|----|----|----|----|----|
| | D | G | E | U | 2 | - | 0 | 2 | T | D | A | 1 | E | C | A | E | H | - | X | X | X |
| Definition | | | | | | | | | | | | | | | | | | | | | |
| Code 1 st (Disk) | | | | | | | | | | | Code 14 th (Operation Temperature) | | | | | | | | | | |
| D : Disk | | | | | | | | | | | C: Standard Grade (0°C ~ +70°C) | | | | | | | | | | |
| Code 2 nd (Feature set) | | | | | | | | | | | W: Industrial Grade (-40°C ~ +85°C) | | | | | | | | | | |
| G : EverGreen Series | | | | | | | | | | | | | | | | | | | | | |
| Code 3 rd ~5 th (Form factor) | | | | | | | | | | | Code 15 th (Internal control) | | | | | | | | | | |
| EU2: U.2 SSD | | | | | | | | | | | A~Z: BGA PCB version. | | | | | | | | | | |
| | | | | | | | | | | | | | | | | | | | | | |
| Code 7 th ~9 th (Capacity) | | | | | | | | | | | Code 16 th (Channel of data transfer) | | | | | | | | | | |
| A28: 128GB | | | B56:256GB | | | C12:512GB | | | | | D: Dual Channels | | | | | | | | | | |
| 01T:1TB | | | 02T:2TB | | | | | | | | Q: Quad Channels | | | | | | | | | | |
| | | | | | | | | | | | E: 8 Channels | | | | | | | | | | |
| Code 10 th ~12 th (Controller) | | | | | | | | | | | Code 17 th (Flash Type) | | | | | | | | | | |
| DA1: ID205, PCIe3.0x4 | | | | | | | | | | | H: Micron 3D TLC | | | | | | | | | | |
| | | | | | | | | | | | | | | | | | | | | | |
| Code 13 th (Flash mode) | | | | | | | | | | | Code 19 th ~ (Customize code) | | | | | | | | | | |
| E: 3D TLC 64 Layer, Micron B17 | | | | | | | | | | | | | | | | | | | | | |
| H: 3D TLC 64 Layer, Micron B17_ industrial | | | | | | | | | | | | | | | | | | | | | |
| | | | | | | | | | | | | | | | | | | | | | |

7. Appendix

REACH



宜鼎國際股份有限公司
Innodisk Corporation
REACH Declaration

Tel: (02) 7703-3000 Fax: (02) 7703-3555 Internet: <http://www.innodisk.com/>

We hereby confirm that the product(s) delivered to

| Innodisk P/N | Description |
|--------------------------------|-------------|
| All Innodisk EM FLASH Products | |

- contain(s) no hazardous substances or constituents exceeding the defined threshold 0.1 % by weight in homogenous material if not otherwise specified, as described in the candidate list table currently including 197 substances and shown on the ECHA website (<http://echa.europa.eu/de/candidate-list-table>).
- contain(s) one or more hazardous substances or constituents exceeding 0.1 % by weight in homogenous material if not otherwise specified in candidate list table. Where the threshold value is exceeded, the substances in question are to be declared in accompanying Appendix A.
- Comply with REACH Annex XVII.

Guarantor

Company name 公司名稱： Innodisk Corporation 宜鼎國際股份有限公司

Company Representative 公司代表人： Randy Chien 簡川勝

Company Representative Title 公司代表人職稱： Chairman 董事長

Date 日期： 2019 / 01 / 31



RoHS



宜鼎國際股份有限公司
Innodisk Corporation

Tel:(02)7703-3000 Fax:(02) 7703-3555 Internet: http://www.innodisk.com/

RoHS 自我宣告書 (RoHS Declaration of Conformity)

Manufacturer Product: All Innodisk EP products

- 一、宜鼎國際股份有限公司（以下稱本公司）特此保證售予貴公司之所有產品，皆符合歐盟 2011/65/EU 及 (EU) 2015/863 關於 RoHS 之規範要求。

Innodisk Corporation declares that all products sold to the company, are complied with European Union RoHS Directive (2011/65/EU) and (EU) 2015/863 requirement.

- 二、本公司同意因本保證書或與本保證書相關事宜有所爭議時，雙方宜友好協商，達成協議。

Innodisk Corporation agrees that both parties shall settle any dispute arising from or in connection with this Declaration of Conformity by friendly negotiations.

| Name of hazardous substance | Limited of RoHS ppm (mg/kg) |
|-----------------------------|-----------------------------|
| 鉛 (Pb) | < 1000 ppm |
| 汞 (Hg) | < 1000 ppm |
| 鎘 (Cd) | < 100 ppm |
| 六價鉻 (Cr 6+) | < 1000 ppm |
| 多溴聯苯 (PBBs) | < 1000 ppm |
| 多溴二苯醚 (PBDEs) | < 1000 ppm |
| 鄰苯二甲酸二(2-乙基己基)酯 (DEHP) | < 1000 ppm |
| 鄰苯二甲酸丁酯苯甲酯 (BBP) | < 1000 ppm |
| 鄰苯二甲酸二丁酯 (DBP) | < 1000 ppm |
| 鄰苯二甲酸二異丁酯 (DIBP) | < 1000 ppm |

立保證書人 (Guarantor)

Company name 公司名稱: Innodisk Corporation 宜鼎國際股份有限公司

Company Representative 公司代表人: Randy Chien 簡川勝

Company Representative Title 公司代表人職稱: Chairman 董事長

Date 日期: 2018 / 07 / 01

